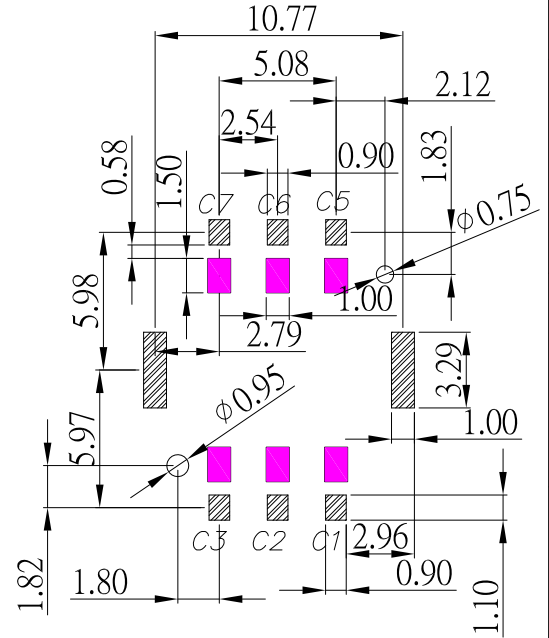
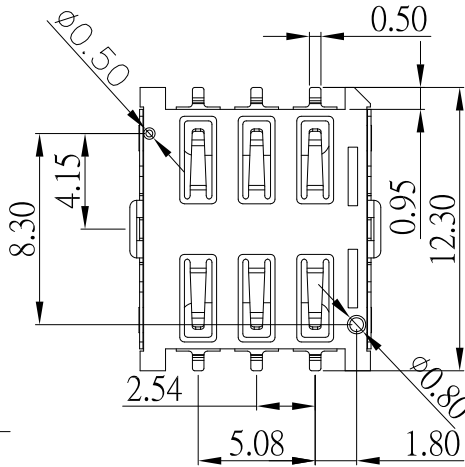
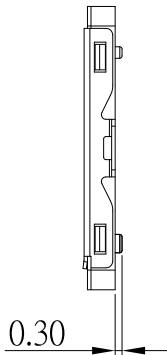
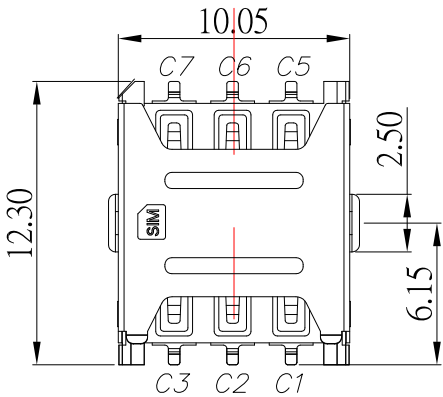
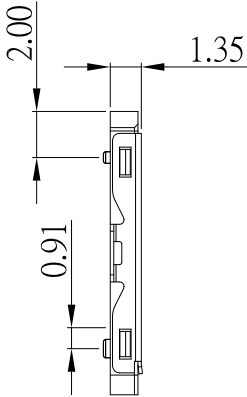
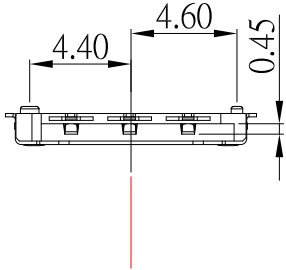


SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



PCB通空位置
 RECOMMENDED PCB LAYOUT

P.C.B LAYOUT MOUNTING PATTERN

MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. CURRENT RATING : 0.5 mA AC / DC MAX.
2. VOLTAGE RATING : 125V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +85°C.
6. STORAGE TEMPERATURE RANGE : -40°C TO +85°C.


東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	02/01/23			
CHECKED BY:	DATE	FINISH	MODLE	Nano SIM CARD NO PUSH 1.35H 有柱
Jacky Chen	02/01/23			
APPROVED BY:	DATE	SCALE	DWG NO.	SIZE
Tony Kao	02/01/23	1 : 1	NSIM-0201G06A-S267	A4
		SHEET NO.	PART NO.	VER
		1 of 1	NSIM-0201G06A-S267	R2